

NOT RECOMMENDED FOR NEW DESIGN **USE DMP3013SFV**



DMP3017SFV

30V P-CHANNEL ENHANCEMENT MODE MOSFET PowerDI3333-8 (Type UX)

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C		
001/	10mΩ @ V _{GS} = -10V	-40A		
-30V	18mΩ @ V _{GS} = -4.5V	-25A		

Description

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

- Backlighting
- Power Management Functions
- DC-DC Converters

Features and Benefits

- Low R_{DS(ON)} ensures on-state losses are minimized
- Small form factor thermally efficient package enables higher density end products
- Occupies just 33% of the board area occupied by SO-8 enabling smaller end product
- **ESD Protected Gate**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free, "Green" Device (Note 3)

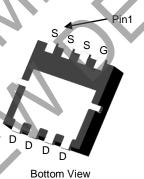
Mechanical Data

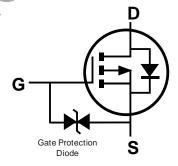
- Case: PowerDI[®]3333-8 (Type UX)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram Terminals: Finish - Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.072 grams (Approximate)





Top View





Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMP3017SFV-7	PowerDI3333-8 (Type UX)	2,000/Tape & Reel
DMP3017SFV-13	PowerDI3333-8 (Type UX)	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



V17 = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 17 = 2017) WW = Week Code (01 to 53)

Document number: DS37534 Rev. 3 - 3



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Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage		V_{DSS}	-30	V	
Gate-Source Voltage		V _{GSS}	±25	V	
Continuous Drain Current (Note 6) V _{GS} = -10V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	-11.5 -9.4	А
Continuous Drain Current (Note 7) V _{GS} = -10V	Steady State	$T_C = +25$ °C $T_C = +70$ °C	I _D	-40 -30	Α
Maximum Continuous Body Diode Forward Curren	t (Note 7)	Is	-30	Α	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 19	I _{DM}	-80	А		
Pulsed Body Diode Forward Current (10µs Pulse,	I _{SM}	-80	Α		
Avalanche Current (Note 8) L = 1mH	I _{AS}	-14	A		
Avalanche Energy (Note 8) L = 1mH	E _{AS}	104	mJ		

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	Pb	0.94	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	134	°C/W
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	Po	1.94	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	65	°C/W
Total Power Dissipation (Note 7)		PD	31	W
Thermal Resistance, Junction to Case (Note 7)		R _θ JC	4.0	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

					~		
Characteristic		Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV _{DSS}	-30			٧	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	7	1	-1	μΑ	$V_{DS} = -24V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	1-1		±10	μΑ	$V_{GS} = \pm 25V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V _{GS(TH)}	-1.0	_	-3.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance			8.5	10	mΩ	$V_{GS} = -10V, I_D = -11.5A$	
Static Dialii-Source Off-Resistance	R _{DS} (ON)	V-	15	18	11122	$V_{GS} = -4.5V$, $I_D = -8.5A$	
Diode Forward Voltage	V _{SD}	_	-0.7	-1.2	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	Ciss	_	2,246	_	pF		
Output Capacitance	Coss	_	352	_	pF	$V_{DS} = -15V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	294	_	pF	T = 1.0MHZ	
Gate Resistance	R_g	_	5.1	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V _{GS} = -5V)	Qg	_	20.5	_	nC		
Total Gate Charge (V _{GS} = -10V)	Qg	_	41	_	nC	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	
Gate-Source Charge	Qgs	_	7.6	_	nC	$V_{DS} = -15V, I_{D} = -11.5A$	
Gate-Drain Charge	Q_{gd}	_	8.0		nC	1	
Turn-On Delay Time	t _{D(ON)}	_	7.5	_	ns		
Turn-On Rise Time	t _R	_	15.4	_	ns	$V_{DD} = -15V, V_{GS} = -10V,$ $R_G = 6\Omega, I_D = -11.5A$	
Turn-Off Delay Time	t _{D(OFF)}	_	45.6	_	ns		
Turn-Off Fall Time	t _F	_	36.8	_	ns		
Reverse Recovery Time	t _{RR}	_	20	_	ns	1 44 54 41/4+ 4004/	
Reverse Recovery Charge	Q _{RR}	_	9.5	_	nC	I _S = -11.5A, dl/dt = 100A/μs	

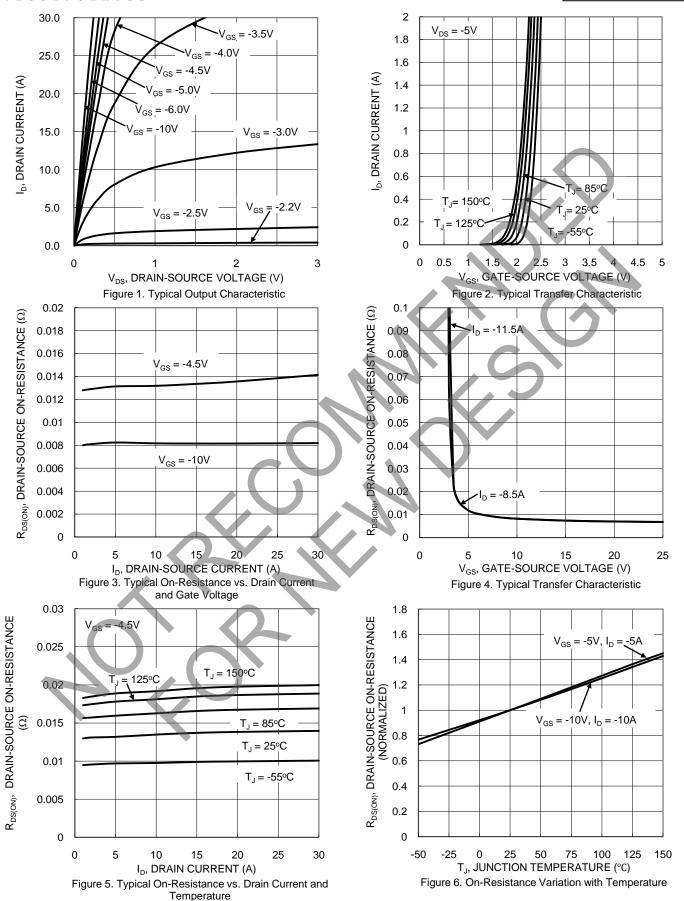
Notes:

- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
- 7. Thermal resistance from junction to soldering point (on the exposed drain pad).
- 8. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.
- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to product testing.



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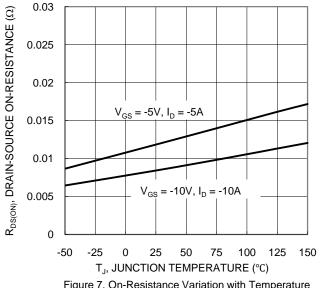


Figure 7. On-Resistance Variation with Temperature

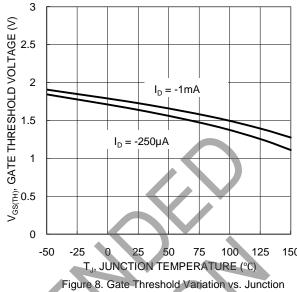


Figure 8. Gate Threshold Variation vs. Junction Temperature

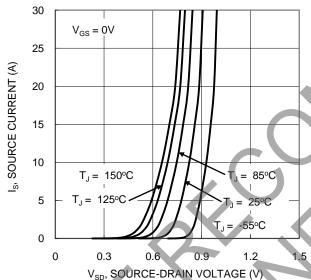
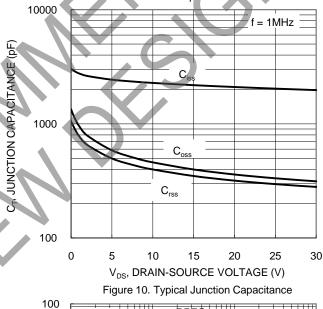
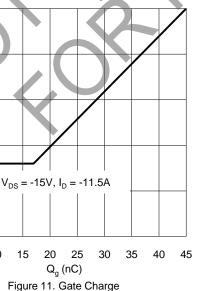
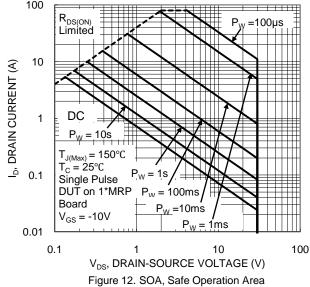


Figure 9. Diode Forward Voltage vs. Current







10

8

2

0

0 5 10

15

20

 $V_{GS}(V)$



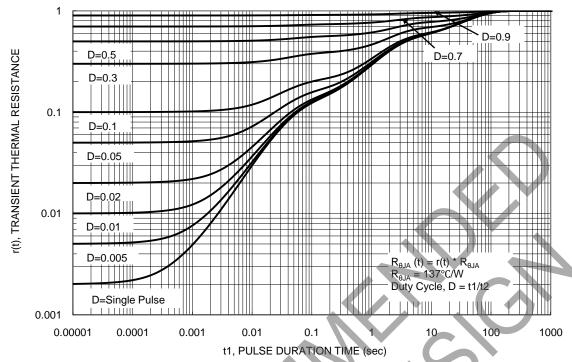


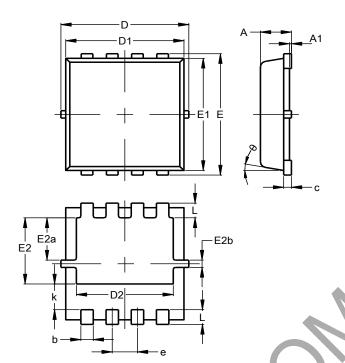
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8 (Type UX)

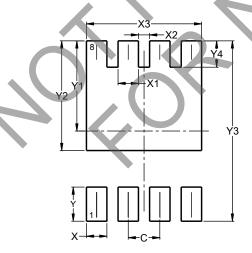


PowerDI3333-8						
(Type UX)						
Dim	Min	Max	Тур			
Α	0.75	0.85	0.80			
A1	0.00	0.05				
b	0.25	0.40	0.32			
C	0.10	0.25	0.15			
D	3.20	3.40	3.30			
D1	2.95	3.15	3.05			
D2	2.30	2.70	2.50			
Ш	3.20	3.40	3.30			
E1	2.95	3.15	3.05			
E2	1.60	2.00	1.80			
E2a	0.95	1.35	1.15			
E2b	0.10	0.30	0.20			
e	0.65 BSC					
k	0.50	0.90	0.70			
Ľ	0.30	0.50	0.40			
θ	0°	12°	10°			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8 (Type UX)



Dimensions	Value (in mm)
С	0.650
Х	0.420
X1	0.420
X2	0.230
Х3	2.370
Υ	0.700
Y1	1.850
Y2	2.250
Y3	3.700
Y4	0.540



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